

The listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A semiconductor device comprising:  
an antenna ~~configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~  
an integrated circuit comprising a thin film transistor;  
a light-receiving element ~~configured to receive a second optical signal;~~ and  
a light-emitting element ~~configured to transmit a third optical signal,~~  
wherein the light-emitting element and the light-receiving element each have a layer for conducting photoelectric conversion using a non-single crystal thin film, and  
wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit on the same substrate.
  
2. (Currently Amended) A semiconductor device comprising:  
an antenna ~~configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~  
an integrated circuit comprising a thin film transistor;  
a light-receiving element ~~configured to receive a second optical signal;~~ and  
a light-emitting element ~~configured to transmit a third optical signal,~~  
wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and  
wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.
  
3. (Currently Amended) A semiconductor device comprising:

~~an antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~

~~an integrated circuit comprising a thin film transistor;~~

~~a light-receiving element configured to receive a second optical signal; and~~

~~a light-emitting element configured to transmit a third optical signal,~~

~~wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and~~

~~wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.~~

4. (Currently Amended) A semiconductor device comprising:

~~an integrated circuit;~~

~~a light-receiving element configured to receive a first optical signal; and~~

~~a light-emitting element configured to transmit a second optical signal,~~

~~wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from an alternating current signal that is input to the connection terminal by an antenna, a demodulation circuit for demodulating the first optical signal received in the light-receiving element, and a logic circuit that conducts arithmetic operation according to the first optical signal that is demodulated to generate a third signal, and~~

~~wherein the light emitting element converts the third signal to the second optical signal, and~~

~~wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.~~

5. (Currently Amended) A semiconductor device comprising:

~~an antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~

an integrated circuit comprising a thin film transistor;  
a light-receiving element ~~configured to receive a second optical signal~~; and  
a light-emitting element ~~configured to transmit a third optical signal~~,  
wherein the light-emitting element and the light-receiving element each have a  
layer for conducting photoelectric conversion using a non-single crystal thin film,  
wherein the antenna, the light-emitting element and the light-receiving element  
are electrically connected to the integrated circuit, ~~[[and]]~~  
wherein the integrated circuit, the light-emitting element and the light-receiving  
element are formed over a first substrate and then separated therefrom, and attached to  
a second substrate, and  
wherein the integrated circuit, the light-emitting element and the light-receiving  
element are formed on the second substrate.

6. (Currently Amended) A semiconductor device comprising:  
an antenna ~~configured to receive a first signal, wherein a power supply voltage is  
generated based on the first signal~~;  
an integrated circuit comprising a thin film transistor;  
a light-receiving element ~~configured to receive a second optical signal~~; and  
a light-emitting element ~~configured to transmit a third optical signal~~,  
wherein the antenna, the light-emitting element and the light-receiving element  
are electrically connected to the integrated circuit, ~~[[and]]~~  
wherein the integrated circuit, the light-emitting element and the light-receiving  
element are formed over a first substrate and then separated therefrom, and attached to  
a second substrate, and  
wherein the integrated circuit, the light-emitting element and the light-receiving  
element are formed on the second substrate.

7. (Currently Amended) A semiconductor device comprising:

~~an antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~

~~an integrated circuit comprising a thin film transistor;~~

~~a light-receiving element configured to receive a second optical signal; and~~

~~a light-emitting element configured to transmit a third optical signal,~~

~~wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, [[and]]~~

~~wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate, and~~

~~wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the second substrate.~~

8. (Currently Amended) A semiconductor device comprising:

~~an integrated circuit;~~

~~a light-receiving element configured to receive a first optical signal; and~~

~~a light-emitting element configured to transmit a second optical signal,~~

~~wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from an alternating current signal that is input to the connection terminal by an antenna, a demodulation circuit for demodulating the first optical signal received in the light-receiving element, and a logic circuit that conducts arithmetic operation according to the first optical signal that is demodulated to generate a third signal,~~

~~wherein the light-emitting element converts the third signal to the second optical signal,~~

~~wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally, [[and]]~~

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the second substrate.

9. (Currently Amended) [[A]] The semiconductor device according to any one of Claims 5 to 8, wherein the first substrate is a glass substrate and the second substrate is a plastic substrate.

10. (Currently Amended) An IC card comprising:  
~~an antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~  
an integrated circuit comprising a thin film transistor;  
~~a light-receiving element configured to receive a second optical signal; and~~  
~~a light-emitting element configured to transmit a third optical signal,~~  
wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and  
wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.

11. (Currently Amended) [[An]] The IC card according to claim 10, wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.

12. (Currently Amended) An IC card comprising:  
an integrated circuit;  
~~a light-receiving element configured to receive a first optical signal; and~~

a light-emitting element ~~configured to transmit a second optical signal,~~  
wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from an alternating current signal that is input to the connection terminal by an antenna, a demodulation circuit ~~for demodulating the first optical signal received in the light-receiving element,~~ and a logic circuit that ~~conducts arithmetic operation according to the first optical signal that is demodulated to generate a third signal, and~~  
~~wherein the light-emitting element converts the third signal to the second optical signal, and~~  
wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.

13. (Currently Amended) An IC card comprising:  
an antenna ~~configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~  
an integrated circuit comprising a thin film transistor;  
a light-receiving element ~~configured to receive a second optical signal; and~~  
a light-emitting element ~~configured to transmit a third optical signal,~~  
wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, ~~[[and]]~~  
wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate, and  
wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the second substrate.

14. (Currently Amended) ~~[[An]]~~ The IC card according to claim 13, wherein the antenna and the integrated circuit in addition to the light-emitting element and the light-

receiving element are formed over the first substrate and then separated therefrom, and attached to the second substrate.

15. (Currently Amended) [[An]] The IC card according to claim 12, wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate.

16. (Original) The IC card according to any one of Claims 13 to 15, wherein the first substrate is a glass substrate and the second substrate is a plastic substrate.